

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1-24. (Canceled).

25. (Currently Amended) An encapsulation method for leadless semiconductor packages, the method comprising:

attaching a plurality of dice to die pads in a plurality of cavities of a ~~lead-frame~~
leadframe, the cavities arranged in a matrix of columns and rows;

electrically connecting the dice to a plurality of conducting portions of the leadframe;

causing a molding material to flow into a first cavity;

causing said molding material to flow from said first cavity into a second cavity adjacent to and in the same column as said first cavity through a first gate of the leadframe that is separately connected between said first cavity and said second cavity; and

causing said molding material to flow from said first cavity into a third cavity adjacent to and in the same row as said first cavity through a second gate of the leadframe that is separately connected between said first cavity and said third cavity.

26. (Previously Presented) The encapsulation method of Claim 25, further comprising causing said molding material to flow from said first cavity into a fourth cavity adjacent to and in the same row as said first cavity.

27. (Previously Presented) The encapsulation method of Claim 25, further comprising:
causing said molding material to flow from said second cavity into a fourth cavity adjacent to and in the same column as said first cavity; and
causing said molding material to flow from said second cavity into a fifth cavity adjacent to and in the same row as said second cavity.

28. (Currently Amended) An encapsulation method comprising:
attaching a plurality of dice to die pads in a plurality of cavities of a leadframe, wherein the cavities are arranged in a matrix having a plurality of columns of cavities and a plurality of rows of cavities;

injecting a molding material along each of the plurality of columns of cavities through a first plurality of gates of said leadframe, wherein each gate of said first plurality of gates is separately connected between corresponding adjacent cavities of said plurality of columns of cavities; and

causing the molding material to flow along each of the plurality of rows of cavities through a second plurality of gate of said leadframe, wherein each gate of said second plurality

of gates is separately connected between corresponding adjacent cavities of said plurality of rows of cavities.

29. (Previously Presented) The encapsulation method according to Claim 28, wherein causing the molding material to flow along each of the plurality of rows of cavities balances a pressure of the molding material injected along each of the plurality of columns of cavities.

30. (Previously Presented) The encapsulation method according to Claim 28, wherein causing the molding material to flow along each of the plurality of rows of cavities drains bubbles induced in the molding material in the plurality of cavities.

31-32. (Canceled).

33. (Previously Presented) The encapsulation method according to Claim 28, further comprising electrically connecting the dice to a plurality of conducting portions of the leadframe before injecting the molding material.

34. (Previously Presented) The encapsulation method according to Claim 28, wherein the molding material flows along each of the plurality of rows of cavities in response to injecting the molding material along each of the plurality of columns of cavities.

35. (Currently Amended) An encapsulation method comprising:

injecting a molding material into a first cavity, from the first cavity through a first gate into a second cavity and from the second cavity through a second gate into a third cavity, ~~wherein first gate and second gate are situated along a first column containing the first cavity, the second cavity and the third cavity are situated along a first column, and wherein the first gate is separately connected between the first cavity and second cavity, and the second gate is separately connected between the second cavity and third cavity;~~

injecting the molding material into a fourth cavity, from the fourth cavity through a third gate into a fifth cavity and from the fifth cavity through a fourth gate into a sixth cavity, wherein ~~the third gate and fourth gate are situated along a second column containing the fourth cavity, the fifth cavity and the sixth cavity are situated along a second column, and wherein the third gate is separately connected between the fourth cavity and fifth cavity, and the fourth gate is separately connected between the fifth cavity and sixth cavity; and~~

causing the molding material to flow from the second cavity through a fifth gate into the fifth cavity, wherein the fifth gate is separately connected between the second cavity and fifth cavity situated along a row containing the second cavity and fifth cavity.

36. (Previously Presented) The encapsulation method according to Claim 35, wherein the molding material flows from the second cavity through the fifth gate into the fifth cavity in response to injecting the molding material along the first column and the second column.

37. (Currently Amended) The encapsulation method of Claim 36, wherein causing the molding material to flow ~~into~~ from the second cavity through the fifth gate into the fifth cavity in response to injection the molding material along the first column and the second column is adapted to balance pressure between cavities in the first column and cavities in a second column

38. (Currently Amended) The encapsulation method of Claim 36, wherein causing the molding material to flow ~~into~~ from the second cavity through the fifth gate into the fifth cavity in response to injection the molding material along the first column and the second column is adapted to drain bubbles induced in the molding material.

39. (Previously Presented) The encapsulation method according to Claim 36, further comprising electrically connecting the dice to a plurality of conducting portions of the leadframe before injecting the molding material.

40. (Previously Presented) The encapsulation method according to Claim 35, wherein the cavities are arranged on a leadframe in a matrix having a plurality of columns of cavities and a plurality of rows of cavities.